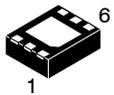


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

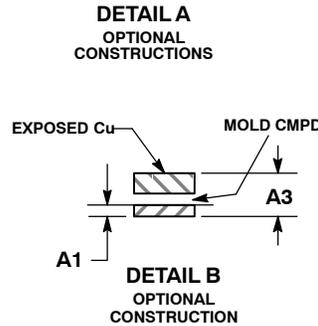
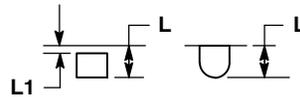
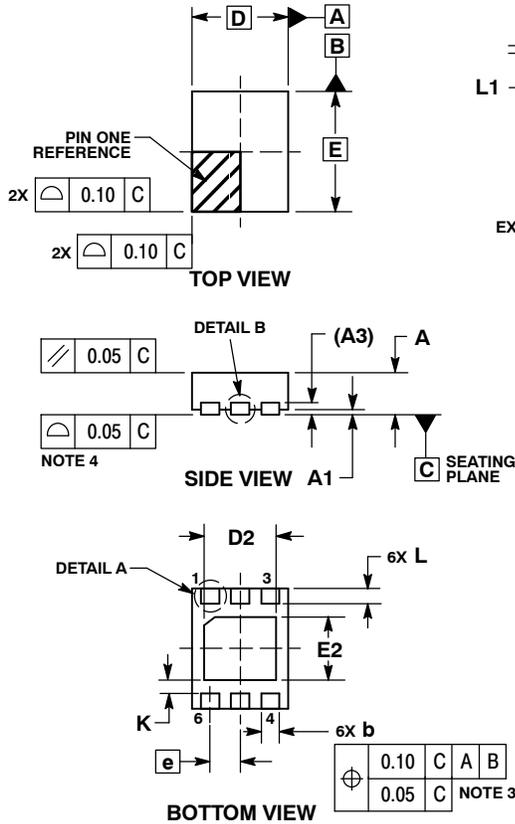
ON Semiconductor®



SCALE 4:1

WDFN6 1.6x2.0, 0.5P CASE 511BV ISSUE O

DATE 17 MAY 2012



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.60	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.40
D	1.60	BSC
D2	1.10	1.30
E	2.00	BSC
E2	0.95	1.15
e	0.50	BSC
K	0.20	---
L	0.15	0.35
L1	---	0.10

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

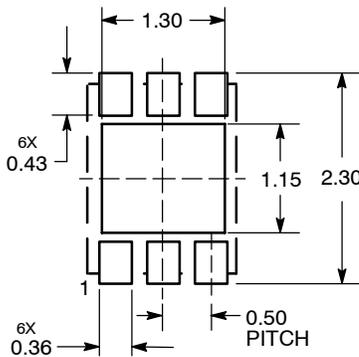
M = Date Code

▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WDFN6, 1.6X2.0, 0.5P	PAGE 1 OF 2

